Fast Recovery Diode

### DA22F2100L

# Panasonic DA22F2100L

## Silicon epitaxial planar type

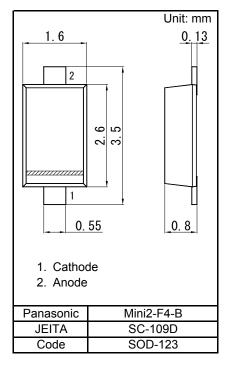
For high speed switching circuits

#### ■ Features

- · Small reverse current IR
- Short reverse recovery time trr
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 3Q

#### ■ Packaging

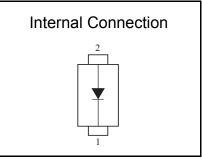
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



#### ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	VRRM	200	V
Non-repetitive peak reverse surge voltage	VRSM	200	V
Forward current	IF	1.0	Α
Non-repetitive peak forward surge current *1	IFSM	15	Α
Junction temperature	Tj	-40 to +150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-40 to +150	°C

Note) \*1: 50 Hz sine wave 1 cycle (Non-repetitive peak current)



Established: 2010-02-12 Revised: 2013-05-23 **Panasonic** 

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# ■ Electrical Characteristics Ta = 25 °C ± 3 °C

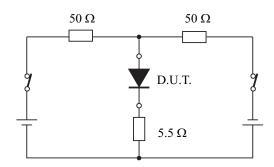
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 1.0 A			0.98	V
Reverse current	IRRM	VRRM = 200 V			10	μΑ
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		60		pF
Reverse recovery time *1	trr	IF= 0.5 A, IR = 1 A			35	ns
		Irr = 0.25 x IR				

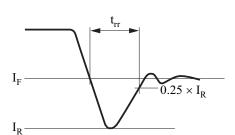
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - This product is sensitive to electric shock (static electricity, etc.).
     Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*1: trr test circuit

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: 2013-05-23





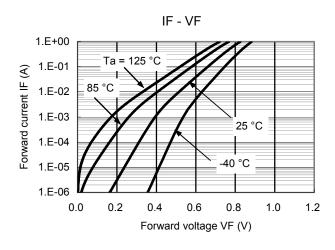
Revision. 3

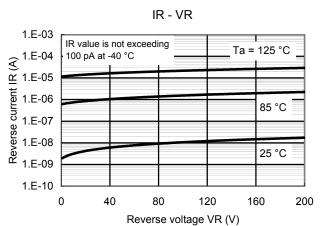
**Panasonic** 

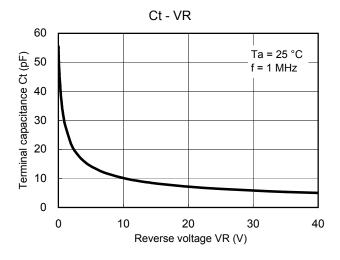
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# Technical Data (reference)







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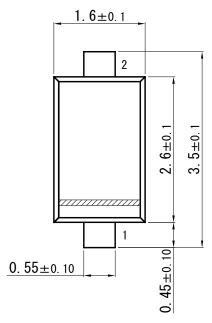
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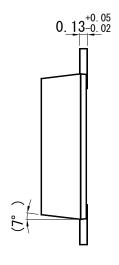
# DA22F2100L

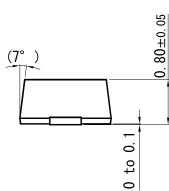
# Mini2-F4-B

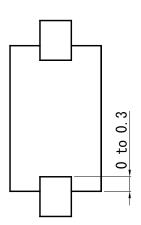
**Panasonic** 

Unit: mm

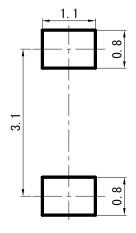








### ■ Land Pattern (Reference) (Unit: mm)



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